TMP303 Easy-to-Use, Low-Power, 1°C, Low-Supply Temperature Range Monitor In Micropackage

1 Features

- Low Power: 5 μA (Maximum)
- SOT-563 Package: 1.60 × 1.60 × 0.6 mm
- Trip Point Accuracy:
  - ±0.2°C (Typical) from -40°C to 125°C
- Push-Pull Output
- Selectable Hysteresis: 1/2/5/10°C
- Supply Voltage Range: 1.4 V to 3.6 V

2 Applications

- Battery Charging
- Battery Thermal Protection
- Consumer Electronics
- Enterprise
- Telecom

3 Description

The TMP303 devices are temperature range monitors that offer design flexibility through an extra small footprint (SOT-563), low power (5 μA maximum) and low supply voltage capability (as low as 1.4 V).

These devices require no additional components for operation; each can function independent of microprocessors or microcontrollers.

There are seven trip points available see Device Options. Trip points can be programmed at the factory to any desired temperature. For applications that require different values, contact your local TI representative.

The OUT pin is a push-pull, active-high output. When the measured temperature is beyond the trip point range, and the Set Output High (SOH) pin is low, the OUT pin is high. The SOH pin is an input pin with an internal pulldown resistor. When the SOH pin is forced high, the OUT pin goes high regardless of the measured temperature.

Device Information(1)

<table>
<thead>
<tr>
<th>PART NUMBER</th>
<th>PACKAGE</th>
<th>BODY SIZE (NOM)</th>
</tr>
</thead>
<tbody>
<tr>
<td>TMP303</td>
<td>SOT-563 (6)</td>
<td>1.60 mm × 1.20 mm</td>
</tr>
</tbody>
</table>

(1) For all available packages, see the orderable addendum at the end of the data sheet.

Typical Trip Threshold Accuracy at -20°C to 125°C
4 Revision History

NOTE: Page numbers for previous revisions may differ from page numbers in the current version.

Changes from Revision H (October 2018) to Revision I

- Changed input pin voltage maximum value in the Absolute Maximum Ratings table from: \((V+) + 0.5\) and \(\leq 4\) to: \((V_S) + 0.3\) and \(\leq 4\) .......................................................... 4
- Changed output pin voltage maximum value in the Absolute Maximum Ratings table from: \((V+) + 0.5\) and \(\leq 4\) to: \((V_S) + 0.3\) and \(\leq 4\) .......................................................... 4

Changes from Revision F (February 2016) to Revision G

- Added TMP303E, TMP303F, TMP303G devices to data sheet .......................................................... 1
- Changed number of Device Options from 4 to 7 .......................................................... 1
- Changed Trip Point Accuracy in Electrical Characteristics from \(T_A = -20\) to 125°C to \(T_A = 60\) to 125°C .......................................................... 5

Changes from Revision E (October 2015) to Revision F

- Added cross reference to Device Option Table. .......................................................... 1
- Added new image for Trip Threshold Accuracy .......................................................... 1
- Added Trip Points covering range -20 to 125°C .......................................................... 5
- Added Trip Accuracy Error vs Temperature graph .......................................................... 6

Changes from Revision D (September 2015) to Revision E

- Changed I/O value of HYST\textsubscript{SET1} row in Pin Functions table .......................................................... 3

Changes from Revision C (September 2015) to Revision D

- Consolidated part number to a generic TMP303 .......................................................... 1
Changes from Revision B (January 2011) to Revision C

- Added ESD Ratings table, Feature Description section, Device Functional Modes section, Application and Implementation section, Power Supply Recommendations section, Layout section, Device and Documentation Support section, and Mechanical, Packaging, and Orderable Information section .............................................................. 1

Changes from Revision A (September 2009) to Revision B

- Added TMP303B device to data sheet................................................................................................................................... 1

5 Device Options

<table>
<thead>
<tr>
<th>DEVICE</th>
<th>TRIP POINTS (°C)</th>
</tr>
</thead>
<tbody>
<tr>
<td>TMP303A</td>
<td>( T_L = 0, T_H = 60 ) (^{(1)} )</td>
</tr>
<tr>
<td>TMP303B</td>
<td>( T_L = 0, T_H = 55 ) (^{(1)} )</td>
</tr>
<tr>
<td>TMP303C</td>
<td>( T_L = -20, T_H = 60 ) (^{(1)} )</td>
</tr>
<tr>
<td>TMP303D</td>
<td>( T_L = -15, T_H = 125 ) (^{(1)} )</td>
</tr>
<tr>
<td>TMP303E</td>
<td>( T_L = 0, T_H = 70 ) (^{(1)} )</td>
</tr>
<tr>
<td>TMP303F</td>
<td>( T_L = 0, T_H = 80 ) (^{(1)} )</td>
</tr>
<tr>
<td>TMP303G</td>
<td>( T_L = 0, T_H = 90 ) (^{(1)} )</td>
</tr>
</tbody>
</table>

\(^{(1)}\) Contact a TI representative for other trip points.

6 Pin Configuration and Functions

<table>
<thead>
<tr>
<th>PIN</th>
<th>I/O</th>
<th>DESCRIPTION</th>
</tr>
</thead>
<tbody>
<tr>
<td>NAME</td>
<td>NO.</td>
<td></td>
</tr>
<tr>
<td>HYST(_{SET0})</td>
<td>1</td>
<td>Digital Input</td>
</tr>
<tr>
<td>GND</td>
<td>2</td>
<td>Ground</td>
</tr>
<tr>
<td>OUT</td>
<td>3</td>
<td>Digital Output</td>
</tr>
<tr>
<td>SOH</td>
<td>4</td>
<td>Digital Input</td>
</tr>
<tr>
<td>( V_S )</td>
<td>5</td>
<td>Power Supply</td>
</tr>
<tr>
<td>HYST(_{SET1})</td>
<td>6</td>
<td>Digital Input</td>
</tr>
</tbody>
</table>
7 Specifications

7.1 Absolute Maximum Ratings

over operating free-air temperature range (unless otherwise noted)\(^{(1)}\)

<table>
<thead>
<tr>
<th>Parameter</th>
<th>MIN</th>
<th>MAX</th>
<th>UNIT</th>
</tr>
</thead>
<tbody>
<tr>
<td>Supply Voltage, (V_S - \text{GND})</td>
<td>4</td>
<td>V</td>
<td></td>
</tr>
<tr>
<td>Input Pins, Voltage SOH, HYST(<em>{\text{SET1}}), HYST(</em>{\text{SET0}})</td>
<td>(-0.5) ((V_S + 0.3)) and (\leq 4)</td>
<td>V</td>
<td></td>
</tr>
<tr>
<td>Output Pin, Voltage OUT</td>
<td>(-0.5) ((V_S + 0.3)) and (\leq 4)</td>
<td>V</td>
<td></td>
</tr>
<tr>
<td>Output Pin, Current OUT</td>
<td>(-55)</td>
<td>8 mA</td>
<td></td>
</tr>
<tr>
<td>Operating Temperature</td>
<td>130</td>
<td>°C</td>
<td></td>
</tr>
<tr>
<td>Junction Temperature, (T_J) max</td>
<td>150</td>
<td>°C</td>
<td></td>
</tr>
<tr>
<td>Storage Temperature, (T_{stg})</td>
<td>(-60)</td>
<td>150</td>
<td>°C</td>
</tr>
</tbody>
</table>

(1) Stresses beyond those listed under Absolute Maximum Ratings may cause permanent damage to the device. These are stress ratings only, which do not imply functional operation of the device at these or any other conditions beyond those indicated under Recommended Operating Conditions. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

7.2 ESD Ratings

<table>
<thead>
<tr>
<th>Electrostatic discharge</th>
<th>VALUE</th>
<th>UNIT</th>
</tr>
</thead>
<tbody>
<tr>
<td>Human-body model (HBM), per ANSI/ESDA/JEDEC JS-001(^{(1)})</td>
<td>(\pm 2000)</td>
<td>V</td>
</tr>
<tr>
<td>Charged-device model (CDM), per JEDEC specification JESD22-C101(^{(2)})</td>
<td>(\pm 1000)</td>
<td>V</td>
</tr>
<tr>
<td>Machine model (MM)</td>
<td>(\pm 200)</td>
<td></td>
</tr>
</tbody>
</table>

(1) JEDEC document JEP155 states that 500-V HBM allows safe manufacturing with a standard ESD control process.
(2) JEDEC document JEP157 states that 250-V CDM allows safe manufacturing with a standard ESD control process.

7.3 Recommended Operating Conditions

over operating free-air temperature range (unless otherwise noted)

<table>
<thead>
<tr>
<th>Parameter</th>
<th>MIN</th>
<th>NOM</th>
<th>MAX</th>
<th>UNIT</th>
</tr>
</thead>
<tbody>
<tr>
<td>(V_S)</td>
<td>1.4</td>
<td></td>
<td>3.6</td>
<td>V</td>
</tr>
<tr>
<td>(T_A)</td>
<td>(-40)</td>
<td></td>
<td>125</td>
<td>°C</td>
</tr>
</tbody>
</table>

7.4 Thermal Information

<table>
<thead>
<tr>
<th>THERMAL METRIC(^{(1)})</th>
<th>TMP303 DRL (SOT-563)</th>
<th>UNIT</th>
</tr>
</thead>
<tbody>
<tr>
<td>(R_{\text{JA}}) Junction-to-ambient thermal resistance</td>
<td>210.3</td>
<td>°C/W</td>
</tr>
<tr>
<td>(R_{\text{JC(top)}}) Junction-to-case (top) thermal resistance</td>
<td>105.0</td>
<td>°C/W</td>
</tr>
<tr>
<td>(R_{\text{JB}}) Junction-to-board thermal resistance</td>
<td>87.5</td>
<td>°C/W</td>
</tr>
<tr>
<td>(\psi_{JT}) Junction-to-top characterization parameter</td>
<td>6.1</td>
<td>°C/W</td>
</tr>
<tr>
<td>(\psi_{JB}) Junction-to-board characterization parameter</td>
<td>87.0</td>
<td>°C/W</td>
</tr>
<tr>
<td>(R_{\text{JC(bot)}}) Junction-to-case (bottom) thermal resistance</td>
<td>N/A</td>
<td>°C/W</td>
</tr>
</tbody>
</table>

(1) For more information about traditional and new thermal metrics, see the Semiconductor and IC Package Thermal Metrics application report, SPRA953.
# 7.5 Electrical Characteristics

At $T_A = -40^\circ$C to 125°C and $V_S = 1.4$ V to 3.6 V, unless otherwise noted.\(^{(1)}\)

<table>
<thead>
<tr>
<th>PARAMETER</th>
<th>CONDITIONS</th>
<th>MIN</th>
<th>TYP</th>
<th>MAX</th>
<th>UNIT</th>
</tr>
</thead>
<tbody>
<tr>
<td>TEMPERATURE MEASUREMENT</td>
<td>$T_A = 55^\circ$C to 60°C, $V_S = 3.3$ V</td>
<td>±0.2</td>
<td>±1</td>
<td>°C</td>
<td></td>
</tr>
<tr>
<td></td>
<td>$T_A = -20$ to 60°C, $V_S = 1.4$ V to 3.6 V</td>
<td>±0.2</td>
<td>±1.5</td>
<td>°C</td>
<td></td>
</tr>
<tr>
<td></td>
<td>$T_A = 60$ to 125°C, $V_S = 1.4$ V to 3.6 V</td>
<td>±0.2</td>
<td>±2.0</td>
<td>°C</td>
<td></td>
</tr>
<tr>
<td></td>
<td>vs Supply</td>
<td>±0.1</td>
<td></td>
<td>°C/V</td>
<td></td>
</tr>
<tr>
<td>Hysteresis</td>
<td>See Bit Setting vs Hysteresis Window</td>
<td>1</td>
<td>10</td>
<td>°C</td>
<td></td>
</tr>
</tbody>
</table>

## HYSTERESIS SET INPUT

- **Input Logic Levels**
  - $V_{IH} = 0.7 \times V_S$
  - $V_{IL} = -0.5 \times V_S$
- **Input Current** $I_{IN} = 0 < V_{IN} < 3.6$ V
- **Output Logic Levels**
  - $V_{OH} > 2$ V, $I_{OH} = 0.5$ mA
  - $V_S > 0.4$ V
  - $V_{OL} > 2$ V, $I_{OL} = 1$ mA
  - $V_S > 0$ V

## SOH INPUT

- **Pulldown Resistor Value** 80, 100, 120 kΩ
- **Input Logic Levels**
  - $V_{IH} = 0.7 \times V_S$
  - $V_{IL} = -0.5 \times V_S$
- **Input Current** $V_{IN} = 3.6$ V
- **Output Logic Levels**
  - $V_{OH} > 2$ V, $I_{OH} = 0.5$ mA
  - $V_S > 0.4$ V
  - $V_{OL} > 2$ V, $I_{OL} = 1$ mA
  - $V_S > 0$ V

## POWER SUPPLY

- **Specified Supply Voltage Range** $V_S = 1.4$ to 3.6 V
- **Power-up Start-up Time** $V_S > 1.4$ V
  - 20, 28, 35 ms
- **Quiescent Current** $I_O$
  - $T_A = -55^\circ$C to 60°C
  - $4$, 5 μA
  - $T_A = -40^\circ$C to 125°C

## TEMPERATURE RANGE

- **Specified Range** $-40$ to 125 °C
- **Operating Range** $-55$ to 130 °C

\(^{(1)}\) 100% of all units are production tested at $T_A = 25^\circ$C. Over temperature specifications are specified by design.

\(^{(2)}\) $T_L$, $T_H$ are device-specific. For example, TMP303A $T_L = 0^\circ$C, $T_H = 60^\circ$C; TMP303B $T_L = 0^\circ$C, $T_H = 55^\circ$C; TMP303C $T_L = -20^\circ$C, $T_H = 60^\circ$C; TMP303D $T_L = -15^\circ$C, $T_H = 125^\circ$C; TMP303E $T_L = 0^\circ$C, $T_H = 70^\circ$C; TMP303F $T_L = 0^\circ$C, $T_H = 80^\circ$C; TMP303G $T_L = 0^\circ$C, $T_H = 90^\circ$C
7.6 Typical Characteristics

At \( V_S = 3.3 \text{ V} \) and \( T_A = 25^\circ \text{C} \), unless otherwise noted.

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**Figure 1.** Trip Accuracy Error vs Temperature

**Figure 2.** Quiescent Current vs Temperature

**Figure 3.** Temperature Step Response in Perfluorinated Fluid at 100°C vs Time

**Figure 4.** Thermal Step Response in Air at 100°C vs Time

**Figure 5.** Trip Threshold Accuracy at -20°C to 125°C

**Figure 6.** Power-Up and Power-Down Transient Response
Typical Characteristics (continued)

At $V_S = 3.3 \text{ V}$ and $T_A = 25^\circ\text{C}$, unless otherwise noted.

Figure 7. Power-Up, Trip, and Power-Down Response

Figure 8. Output Logic Level Low vs Temperature

Figure 9. Output Logic Level High vs Temperature
8 Detailed Description

8.1 Overview

The TMP303 devices are temperature switches used in battery-powered applications that require accurate monitoring of a very specific temperature range from 0°C to 60°C (TMP303A), 0°C to 55°C (TMP303B), –20°C to 60°C (TMP303C), –15°C to 125°C (TMP303D), 0°C to 70°C (TMP303E), 0°C to 80°C (TMP303F) or 0°C to 90°C (TMP303G). This functionality is accomplished through the preset trip window and two hysteresis bits, HYST$_{SET0}$ and HYST$_{SET1}$. The preset trip window temperature thresholds are configured at the factory; for other trip points, contact a TI representative. Table 1 summarizes the bit setting versus hysteresis temperature window.

<table>
<thead>
<tr>
<th>HYST$_{SET1}$</th>
<th>HYST$_{SET0}$</th>
<th>HYSTERESIS</th>
</tr>
</thead>
<tbody>
<tr>
<td>GND</td>
<td>GND</td>
<td>1°C</td>
</tr>
<tr>
<td>GND</td>
<td>V$_S$</td>
<td>2°C</td>
</tr>
<tr>
<td>V$_S$</td>
<td>GND</td>
<td>5°C</td>
</tr>
<tr>
<td>V$_S$</td>
<td>V$_S$</td>
<td>10°C</td>
</tr>
</tbody>
</table>

8.2 Functional Block Diagram

![Functional Block Diagram](image)
8.3 Feature Description

8.3.1 HYST\textsubscript{SET0}, HYST\textsubscript{SET1}, and SOH Functionality

The TMP303A temperature trip window resides within the range of 0°C to 60°C, the TMP303B within 0°C to 55°C, the TMP303C within –20°C to 60°C, the TMP303D within –15°C to 125°C, the TMP303E within 0°C to 70°C, the TMP303F within 0°C to 80°C, and the TMP303G within 0°C to 90°C. When any of these trip thresholds is crossed, the output (OUT) changes state from low to high. OUT does not return to its original low state until the temperature crosses the hysteresis threshold and returns within the range of the temperature trip window.

As an example, if the TMP303A is configured with a 10°C hysteresis window (that is, HYST\textsubscript{SET0} = HYST\textsubscript{SET1} = V\textsubscript{S}), the output does not return to its low state until the temperature either crosses (T\textsubscript{L} + hysteresis) = 10°C or (T\textsubscript{H} – hysteresis) = 50°C. The Set Output High (SOH) pin is intended to add test functionality to verify the connectivity of the output (OUT) pin to the system controller or other temperature response system. The SOH pin is internally pulled down to ground with a 100-kΩ resistor. If the SOH pin is grounded or left floating, it has no effect on the behavior of the TMP303A. If the SOH pin is pulled high, the TMP303A immediately forces the output high, regardless of temperature.

**NOTE**

This response occurs even if the temperature falls within the 0°C to 60°C temperature window.

Figure 10 shows this design in graphical form.

![Graph showing TMP303A Output Transfer Curves With Hysteresis Change from 10°C to 5°C and SOH Functionality](image-url)
Feature Description (continued)

8.3.2 TMP303 Power Up and Timing

At device power up, the TMP303 exerts OUT = high, and typically requires 26 ms to return to a low state only if the temperature falls within the hysteresis window set by HYST_{SET0} and HYST_{SET1}.

The tolerance of the thermal response time is largely a result of the differences in conversion time, which varies from 20 ms to 35 ms; likewise, this conversion does not take place after a power cycle until the supply voltage has reached a level of at least 1.4 V. This sequence is illustrated in Figure 11.

![Figure 11. TMP303A Start-Up Delay vs Output Voltage (HYST_{SET0} = HYST_{SET1} = V_S)](image)

After the TMP303 powers up, all successive thermal response results for the device are achieved in a time frame of 0.985 s to 1 s. This period is the minimum time frame required for the push-pull output (OUT) to change its state from high to low (or conversely) when the device is active.
Feature Description (continued)

A maximum low output voltage is defined as a voltage level equivalent to \((0.2 \times V_S)\); likewise, a minimum high-output voltage is defined as \((0.8 \times V_S)\). The timing associated with start-up time and conversion is shown in Figure 12.

![Graph showing start-up and conversion timing](image)

**Figure 12.** TMP303A Start-Up and Conversion Timing \((HYST_{SET0} = HYST_{SET1} = V_S)\)

### 8.4 Device Functional Modes

The TMP303 family of devices has a single functional mode. Normal operation for the TMP303 family of devices occurs when the power-supply voltage applied between the \(V_S\) pin and GND is within the specified operating range of 1.4 to 3.6 V. The temperature threshold is configured at the factory and the hysteresis is selected by connecting the \(HYST_{SET0}\) and \(HYST_{SET1}\) pins to either the GND or \(V_S\) pins (see Table 1).
9  Application and Implementation

NOTE
Information in the following applications sections is not part of the TI component specification, and TI does not warrant its accuracy or completeness. TI’s customers are responsible for determining suitability of components for their purposes. Customers should validate and test their design implementation to confirm system functionality.

9.1 Application Information

The TMP303 family of devices is simple to configure. The TMP303 contains an active high, push-pull output stage and does not require a pullup resistor to \( V_S \) for proper operation. The only external component that the device requires is a bypass capacitor. TI strongly recommends using a 0.1-µF capacitor, placed as close as possible to the supply pin.

9.2 Typical Applications

9.2.1 TMP303 Typical Configuration

Figure 13 shows the typical circuit configuration for the TMP303 family of devices. These devices have preprogrammed trip-points. Select the TMP303 device that meets the application temperature trip requirement.

9.2.1.1 Design Requirements

The TMP303 is a temperature switch commonly used to signal a microprocessor in the event of an over or under temperature condition. The temperature that the TMP303 issues a output is determined by the device preset trip window. The TMP303 issues an output when the temperature threshold is exceeded. To avoid the TMP303 signaling the microprocessor as soon as the temperature drops below the temperature threshold the TMP303 has a built-in hysteresis. The amount of hysteresis is determined by the hysteresis pins, \( \text{HYST}_{\text{SET0}} \) and \( \text{HYST}_{\text{SET1}} \). These pins are digital inputs and must be tied either high or low, according to Table 1.

9.2.1.2 Detailed Design Procedure

Select the appropriate TMP303 device that matches the application requirements; see the Device Options table for different trip point ranges. Connect the \( \text{HYST}_{\text{SET0}} \) and \( \text{HYST}_{\text{SET1}} \) pins according to the application requirements; see Table 1. In Figure 13 the TMP303 device is configured with a 1°C hysteresis window (that is, \( \text{HYST}_{\text{SET0}} = \text{HYST}_{\text{SET1}} = \text{GND} \)). Place a 0.1-µF bypass capacitor close to the TMP303 device to reduce the noise coupled from the power supply.
Typical Applications (continued)

9.2.1.3 Application Curves

Figure 14 and Figure 15 show the TMP303A power-on response with the ambient temperature ($T_A$) less than 60°C and greater than 60°C respectively. TMP303B, TMP303C, TMP303D, TMP303E, TMP303F, and TMP303G devices behave similarly with regards to power-on response with $T_A$ below or above the trip point.

9.2.2 TMP303 With Switches

Figure 16 shows the most generic implementation of the TMP303 family of devices. Switches are shown connecting the HYST$\text{SET}_0$ and HYST$\text{SET}_1$ pins to either $V_S$ or GND. The use of switches is not a requirement; the switches are shown only to illustrate the various pin connection combinations. In practice, connecting the HYST$\text{SET}_0$ and HYST$\text{SET}_1$ pins to ground or directly to the $V_S$ pin is sufficient and minimizes board space and cost. If additional flexibility is desired, connections from the HYST$\text{SET}_0$ and HYST$\text{SET}_1$ pins can be made through 0-$\Omega$ resistors, which can be either populated or not, depending upon the desired connection.
Typical Applications (continued)

9.2.3 Simple Fan Controller

The circuit in Figure 17 senses system temperature and turns a cooling fan on when the sensor's temperature exceeds a preselected value. The TMP303 device can be used directly to control the fan. The OUT pin is active high, and it can be used directly to drive the DC fan. When temperature is within the temperature limits of the system, the fan turns off, and when the temperature exceeds the trip-point, the fan turns on. In this example, the TMP303A device is used and is configured with a 1°C hysteresis window (HYSTSET0 = HYSTSET1 = GND). The TMP303A high trip-point is 60°C. When this trip-point temperature is exceeded, the output (OUT) changes state from low to high. The output does not return to its low state until the temperature decreases below (TH - hysteresis) = 59°C.

![Figure 17. Simple Fan Controller](image-url)
Typical Applications (continued)

9.2.4 Wireless Fixed Temperature Heat Detector

Heat detectors are needed in building automation. Conventional heat detectors need cables to supply power and send the information back to a central system. Adding cables can be very costly and technically challenging in old buildings, this leads to wireless battery operated heat detectors as preferred solutions. Running on battery requires designing a very low power system for long haul. TMP303 can be used to design a low power heat detector due to its very low quiescent current (5 µA maximum). The TMP303 device does not require any additional components and can be interfaced with the MCU using only one GPIO. As an example, a wireless transceiver with internal MCU can be used to monitor the TMP303 and communicate with a central system or turn on an alarm in case of temperatures exceeding the trip-point. Figure 18 shows typical connections.

![Figure 18. Wireless Fixed Temperature Heat Detector](image-url)
10 Power Supply Recommendations

The TMP303 family of devices is designed to operate from a single power supply within the range of 1.4 V to 3.6 V. No specific power supply sequencing with respect to any of the input or output pins is required.

11 Layout

11.1 Layout Guidelines

Mount the TMP303 to a PCB as shown in Figure 19. For this example the \( \text{HYST}_{\text{SET0}} \) and \( \text{HYST}_{\text{SET1}} \) pins are connected directly to ground. Connecting these pins to ground configures the device for 1°C hysteresis. The \( \text{SOH} \) pin is grounded in this layout. Leaving this pin floating has no effect on the behavior of the TMP303.

- Bypass the \( V_S \) pin to ground with a low-ESR ceramic bypass capacitor. The typical recommended bypass capacitance is a 0.1-\( \mu \)F ceramic capacitor with a X5R or X7R dielectric. The optimum placement is closest to the \( V_S \) and GND pins of the device. Take care in minimizing the loop area formed by the bypass-capacitor connection, the \( V_S \) pin, and the GND pin of the IC. Additional bypass capacitance can be added to compensate for noisy or high-impedance power supplies.

- The OUT pin is a push-pull, active-high output and does not require a pullup resistor to \( V_S \).

11.2 Layout Example

![PCB Layout Example](https://www.ti.com/lit/an/sbos486i/sbos486i.pdf)

**Figure 19. PCB Layout Example**
12 Device and Documentation Support

12.1 Receiving Notification of Documentation Updates
To receive notification of documentation updates, navigate to the device product folder on ti.com. In the upper right corner, click on Alert me to register and receive a weekly digest of any product information that has changed. For change details, review the revision history included in any revised document.

12.2 Community Resources
The following links connect to TI community resources. Linked contents are provided “AS IS” by the respective contributors. They do not constitute TI specifications and do not necessarily reflect TI's views; see TI's Terms of Use.

**TI E2E™ Online Community**  *TI's Engineer-to-Engineer (E2E) Community.* Created to foster collaboration among engineers. At e2e.ti.com, you can ask questions, share knowledge, explore ideas and help solve problems with fellow engineers.

**Design Support**  *TI's Design Support* Quickly find helpful E2E forums along with design support tools and contact information for technical support.

12.3 Trademarks
E2E is a trademark of Texas Instruments.
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12.4 Electrostatic Discharge Caution
This integrated circuit can be damaged by ESD. Texas Instruments recommends that all integrated circuits be handled with appropriate precautions. Failure to observe proper handling and installation procedures can cause damage.

ESD damage can range from subtle performance degradation to complete device failure. Precision integrated circuits may be more susceptible to damage because very small parametric changes could cause the device not to meet its published specifications.

12.5 Glossary
**SLYZ022 — TI Glossary.**
This glossary lists and explains terms, acronyms, and definitions.

13 Mechanical, Packaging, and Orderable Information
The following pages include mechanical, packaging, and orderable information. This information is the most current data available for the designated devices. This data is subject to change without notice and revision of this document. For browser-based versions of this data sheet, refer to the left-hand navigation.
## PACKAGING INFORMATION

<table>
<thead>
<tr>
<th>Orderable Device</th>
<th>Status (1)</th>
<th>Package Type</th>
<th>Package Drawing</th>
<th>Pins</th>
<th>Package Qty</th>
<th>Eco Plan (2)</th>
<th>Lead finish/ Ball material (6)</th>
<th>MSL Peak Temp (3)</th>
<th>Op Temp (°C)</th>
<th>Device Marking (4/5)</th>
<th>Samples</th>
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<tbody>
<tr>
<td>TMP303ADRLR</td>
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<td>NIPDAU</td>
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</table>

1. The marketing status values are defined as follows:  
   **ACTIVE**: Product device recommended for new designs.  
   **LIFEBUY**: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.  
   **NRND**: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.  
   **PREVIEW**: Device has been announced but is not in production. Samples may or may not be available.  
   **OBSOLETE**: TI has discontinued the production of the device.

2. **RoHS**: TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".  
   **RoHS Exempt**: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.  
   **Green**: TI defines "Green" to mean the content of Chlorine (Cl) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

3. **MSL, Peak Temp.**: The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

4. There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

5. Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.
(6) Lead finish/Ball material - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

**Important Information and Disclaimer:** The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

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**TAPE AND REEL INFORMATION**

**REEL DIMENSIONS**

- Reel Diameter
- Reel Width (W1)

**TAPE DIMENSIONS**

- A0: Dimension designed to accommodate the component width
- B0: Dimension designed to accommodate the component length
- K0: Dimension designed to accommodate the component thickness
- W: Overall width of the carrier tape
- P1: Pitch between successive cavity centers

**QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE**

- Sprocket Holes
- Pocket Quadrants
- User Direction of Feed

*All dimensions are nominal*

<table>
<thead>
<tr>
<th>Device</th>
<th>Package Type</th>
<th>Package Drawing</th>
<th>Pins</th>
<th>SPQ</th>
<th>Reel Diameter (mm)</th>
<th>Reel Width W1 (mm)</th>
<th>A0 (mm)</th>
<th>B0 (mm)</th>
<th>K0 (mm)</th>
<th>P1 (mm)</th>
<th>W (mm)</th>
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### TAPE AND REEL BOX DIMENSIONS

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<th>Package Type</th>
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<th>Pins</th>
<th>SPQ</th>
<th>Length (mm)</th>
<th>Width (mm)</th>
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<td>210.0</td>
<td>185.0</td>
<td>35.0</td>
</tr>
</tbody>
</table>

*All dimensions are nominal*
NOTES:

1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.

2. This drawing is subject to change without notice.

3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm per side.

4. Reference JEDEC registration MO-293 Variation UAAD
NOTES: (continued)

5. Publication IPC-7351 may have alternate designs.
6. Solder mask tolerances between and around signal pads can vary based on board fabrication site.
7. Land pattern design aligns to IPC-610, Bottom Termination Component (BTC) solder joint inspection criteria.
NOTES: (continued)

8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.

9. Board assembly site may have different recommendations for stencil design.
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